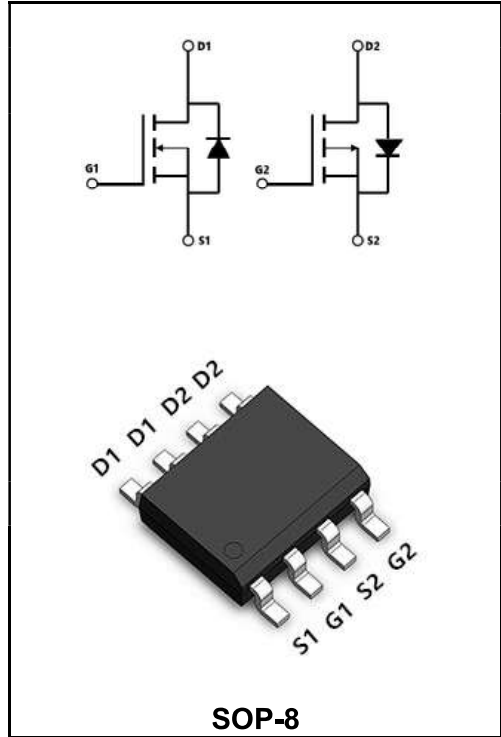


40V N+P-CHANNEL ENHANCEMENT MODE MOSFET

MAIN CHARACTERISTICS

I_D	20A
V_{DSS}	40V
$R_{DS(on)-typ}(@V_{GS}=10V)$	< 21mΩ (Type:16 mΩ)
$R_{DS(on)-typ}(@V_{GS}=4.5V)$	< 25mΩ (Type:18 mΩ)
I_D	-18A
V_{DSS}	-40V
$R_{DS(on)-typ}(@V_{GS}=-10V)$	< 38mΩ (Type:30 mΩ)
$R_{DS(on)-typ}(@V_{GS}=-4.5V)$	< 62mΩ (Type:46 mΩ)



Application

- ◆Wireless charging
- ◆Boost driver
- ◆Brushless motor

Product Specification Classification

Part Number	Package	Marking	Pack
YFW20G04S	SOP-8	YFW 20G04S XXXXX	3000PCS/Tape

Maximum Ratings at Tc=25°C unless otherwise specified

Characteristics	Symbols	Value		Units
		N-Ch	P-Ch	
Drain-Source Voltage	V_{DS}	40	-40	V
Gate - Source Voltage	V_{GS}	±20	±20	V
Maximum Junction Temperature	T_J	150		°C
Storage Temperature Range	T_{STG}	-55 to +150		°C
Diode Continuous Forward Current	I_S	2	-2	A
Pulse Drain Current Tested $V_{GS}=10V(N), V_{GS}=-10V(P)$	I_{DP}	30	-22	A
Continuous Drain Current $T_A=25°C$	I_D	7.5	-5.5	A
Continuous Drain Current $T_A=70°C$		6	-4.5	
Maximum Power Dissipation $T_A=25°C$	P_D	2	2	W
Maximum Power Dissipation $T_A=70°C$		1.3	1.3	
Thermal Resistance-Junction to Lead	$R_{θJL}$	50	50	°C/W
Thermal Resistance Junction-Ambient $t \leq 10s$	$R_{θJA}$	62.5	62.5	°C/W
Steady State b		110	110	
Avalanche Current, Single pulse $L=0.5m$	$I_{AS a}$	10	10	A
Avalanche Energy, Single pulse $L=0.5m$	$E_{AS a}$	25	25	mJ

N-Channel Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Characteristics	Test Condition	Symbols	Min	Typ	Max	Units
Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250uA	BV_{DSS}	40	-	-	V
Zero Gate Voltage Drain Current	V _{DS} =32V, V _{GS} =0V	I_{DSS}	-	-	1	mA
	T _J =85°C		-	-	30	
Gate -Threshold Voltage	V _{DS} =V _{GS} , I _D =250uA	V_{GS(th)}	1.5	2	2.5	V
Gate Leakage Current	V _{GS} =±20V, V _{DS} =0V	I_{GSS}	-	-	±100	nA
Drain-Source On-state Resistance	V _{GS} =10V, I _D =6A	R_{DS(ON)} c	-	16	21	mW
	V _{GS} =4.5V, I _D =5A		-	18	25	
Diode Forward Voltage	I _{SD} =1A, V _{GS} =0V	V_{SD} c	-	0.75	1.1	V
Reverse Recovery Time	I _{DS} =6A, dI _{SD} /dt=100A/ms	t_{rr}	-	13	-	ns
Reverse Recovery Charge		Q_{rr}	-	8.7	-	nC
Gate Resistance	V _{DS} =0V, V _{GS} =0V, f=1MHz	R_g	-	2.5	-	W
Input Capacitance	V _{GS} =0V V _{DS} =20V Frequency=1.0MHz	C_{iss}	-	815	-	pF
Output Capacitance		C_{oss}	-	95	-	
Reverse Transfer Capacitance		C_{rss}	-	60	-	
Turn-on delay time	V _{DD} =20V R _L =20W I _{DS} = 1A V _{GEN} =10V R _G = 6W	t_{d(on)}	-	7.8	-	ns
Turn-on Rise Time		T_r	-	6.9	-	
Turn-Off Delay Time		t_{d(OFF)}	-	22.4	-	
Turn-Off Fall Time		t_f	-	4.8	-	
Total Gate Charge	V _{DS} =20V, V _{GS} =10V, I _{DS} =6A	Q_g	-	15.7	-	
Total Gate Charge	V _{DS} =20V V _{GS} =4.5V I _{DS} =6A	Q_g	-	7.5	22	nC
Threshold Gate Charge		Q_{gth}	-	1.85	10.5	
Gate-Source Charge		Q_{gs}	-	3.24	-	
Gate-Drain Charge		Q_{gd}	-	2.75	-	

Note c: Pulse test ; pulse width£300ms, duty cycle£2%.

Note d: Guaranteed by design, not subject to production testing.

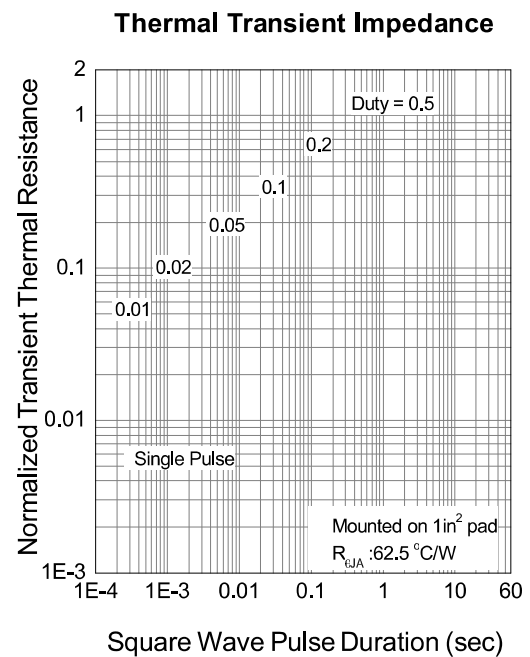
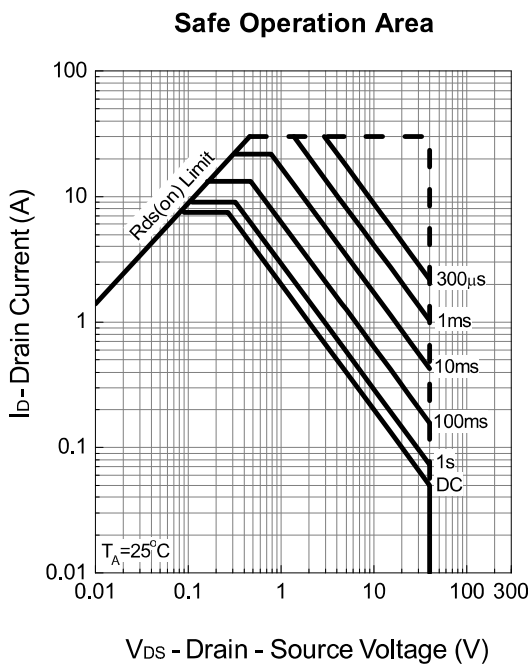
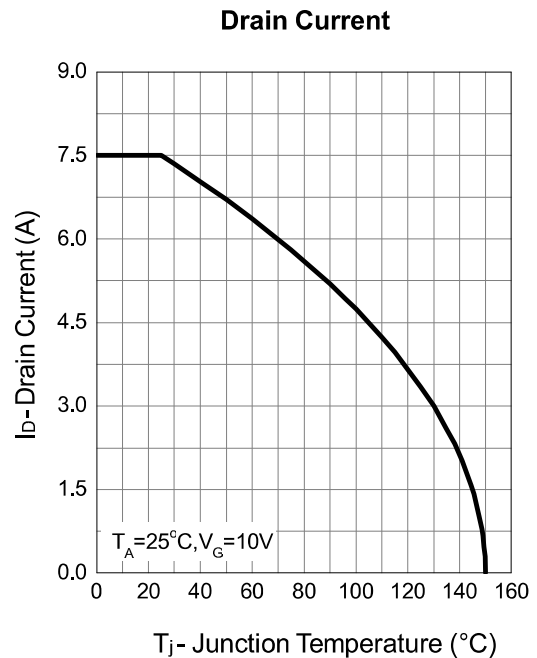
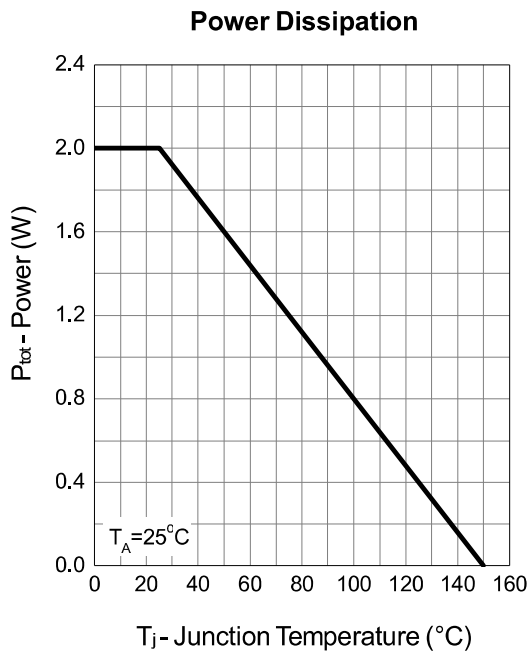
P-Channel Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Characteristics	Test Condition	Symbols	Min	Typ	Max	Units
Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =-250uA	BV_{DSS}	-40	-	-	V
Zero Gate Voltage Drain Current	V _{DS} =-32V, V _{GS} =0V	I_{DSS}	-	-	-1	mA
	T _J =85°C		-	-	-30	mA
Gate -Threshold Voltage	V _{DS} =V _{GS} , I _D =-250uA	V_{GS(th)}	1.5	-2	-2.5	V
Gate Leakage Current	V _{GS} =±20V, V _{DS} =0V	I_{GSS}	-	-	±100	nA
Drain-Source On-state Resistance	V _{GS} =-10V, I _D =-5.5A	R_{DS(ON)} c	-	30	38	mW
	V _{GS} =-4.5V, I _D =-3.5A		-	46	65	
Diode Forward Voltage	I _{SD} =-1A, V _{GS} =0V	V_{SD} c	-	-0.75	-1	V
Reverse Recovery Time	I _{DS} =-5.5A, dI _{SD} /dt=100A/ms	t_{rr}	-	15	-	ns
Reverse Recovery Charge		Q_{rr}	-	8	-	nC
Gate Resistance	V _{DS} =0V, V _{GS} =0V, f=1MHz	R_g	-	8	-	W
Input Capacitance	V _{GS} =0V V _{DS} =-20V Frequency=1.0MHz	C_{iss}	-	668	-	pF
Output Capacitance		C_{oss}	-	98	-	
Reverse Transfer Capacitance		C_{rss}	-	72	-	
Turn-on delay time	V _{DD} =-20V R _L =20W I _{DS} =-1A V _{GEN} =-10V R _G =6W	t_{d(on)}	-	8.7	-	ns
Turn-on Rise Time		T_r	-	7	-	
Turn-Off Delay Time		t_{d(OFF)}	-	31	-	
Turn-Off Fall Time		t_f	-	17	-	
Total Gate Charge	V _{DS} =-20V, V _{GS} =-10V, I _{DS} =-5.5A	Q_g	-	15	-	nC
Total Gate Charge	V _{DS} =-20V V _{GS} =-4.5V I _{DS} =-5.5A	Q_g	-	7.5	-	
Threshold Gate Charge		Q_{gth}	-	1.4	-	
Gate-Source Charge		Q_{gs}	-	2.4	-	
Gate-Drain Charge		Q_{gd}	-	3.5	-	

Note c: Pulse test; pulse width£300ms, duty cycle£2%.

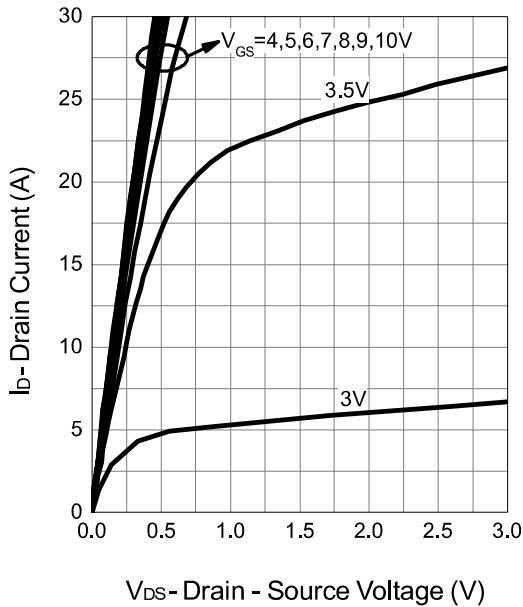
Note d: Guaranteed by design, not subject to production testing.

N Channel Typical Operating Characteristics

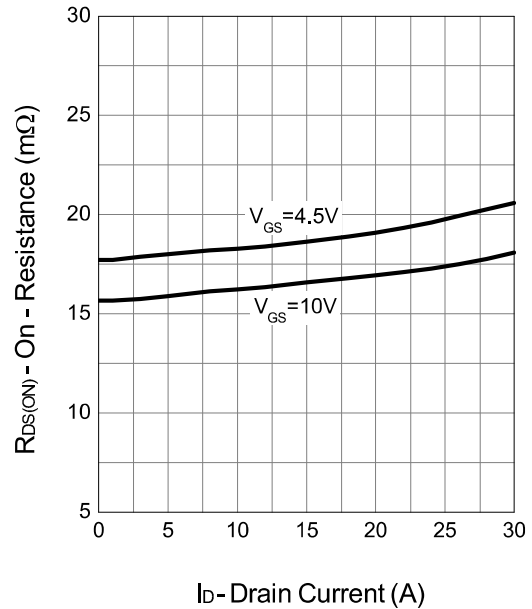


N Channel Typical Operating Characteristics (Cont.)

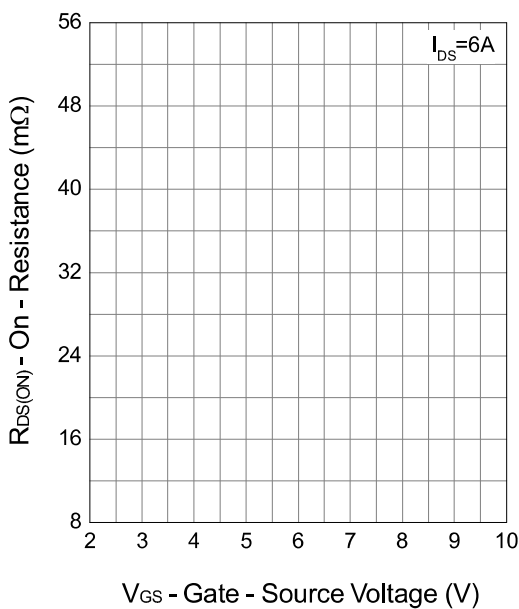
Output Characteristics



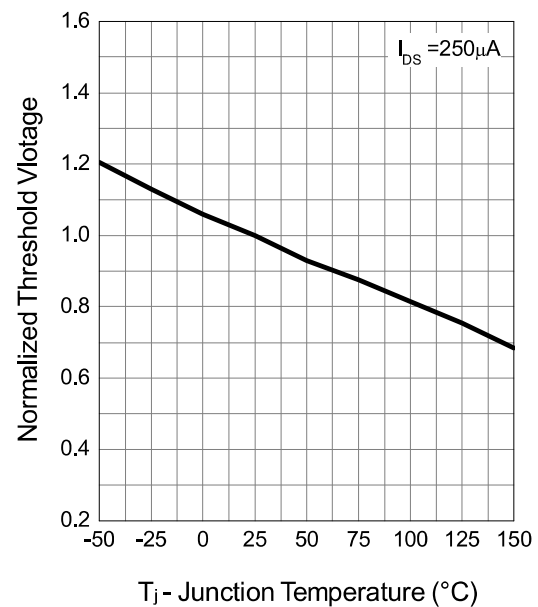
Drain-Source On Resistance



Gate-Source On Resistance

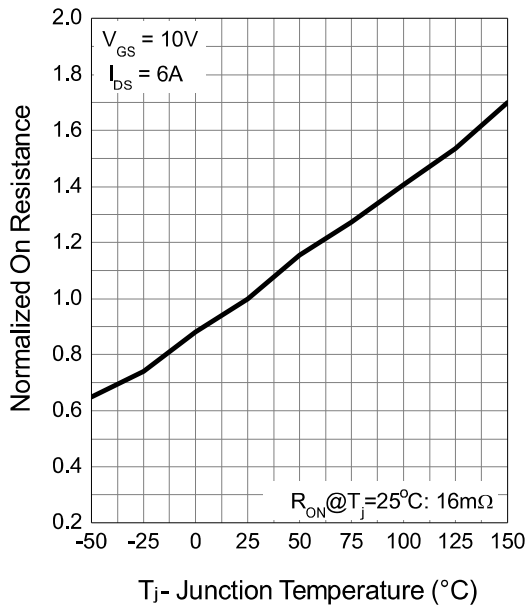


Gate Threshold Voltage

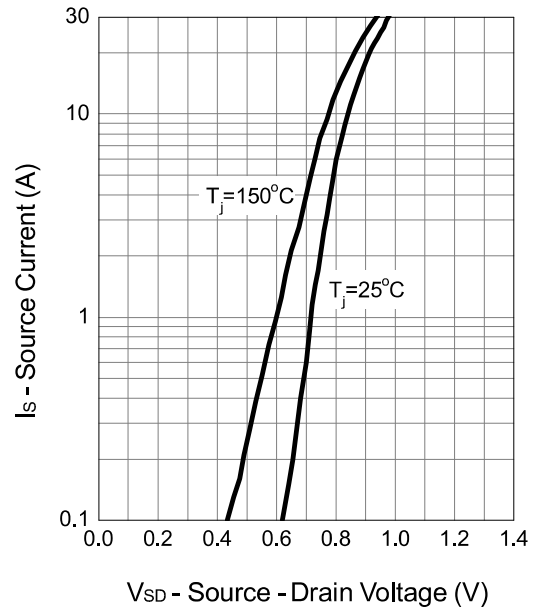


N Channel Typical Operating Characteristics (Cont.)

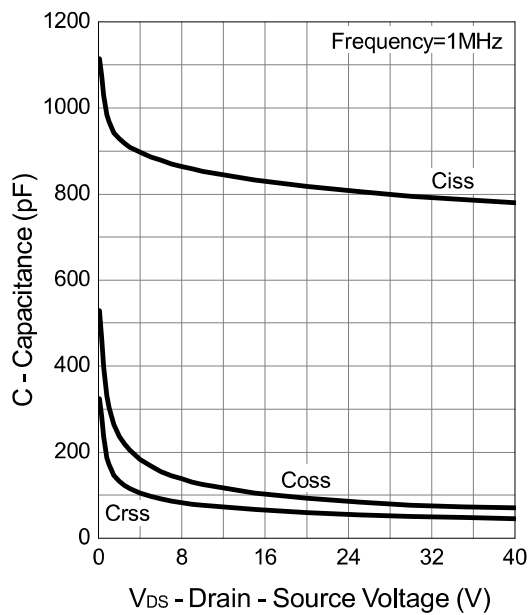
Drain-Source On Resistance



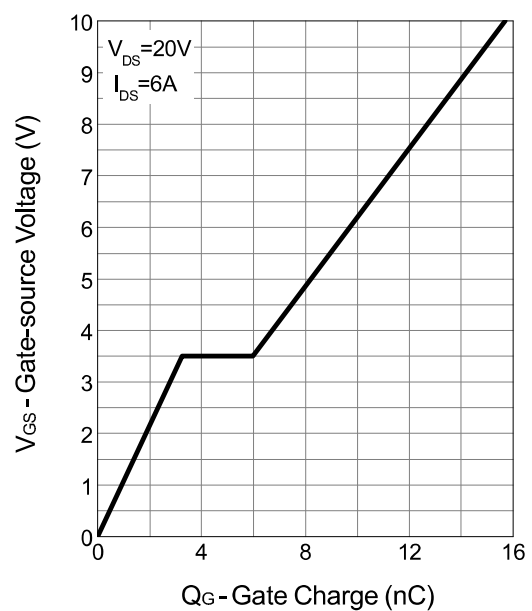
Source-Drain Diode Forward



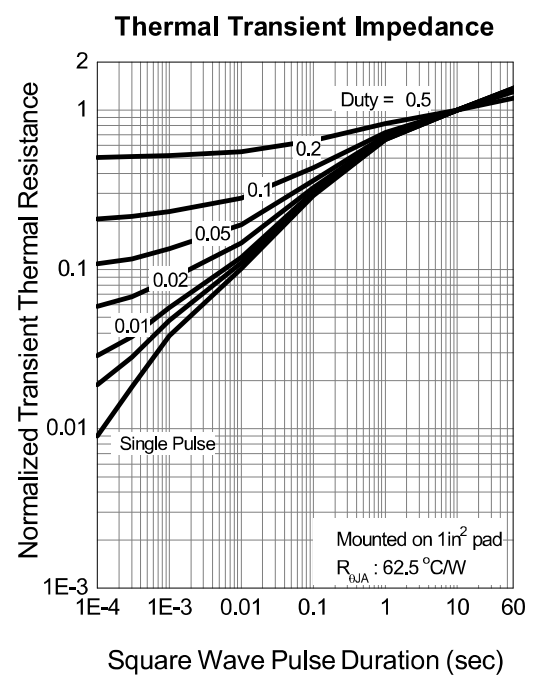
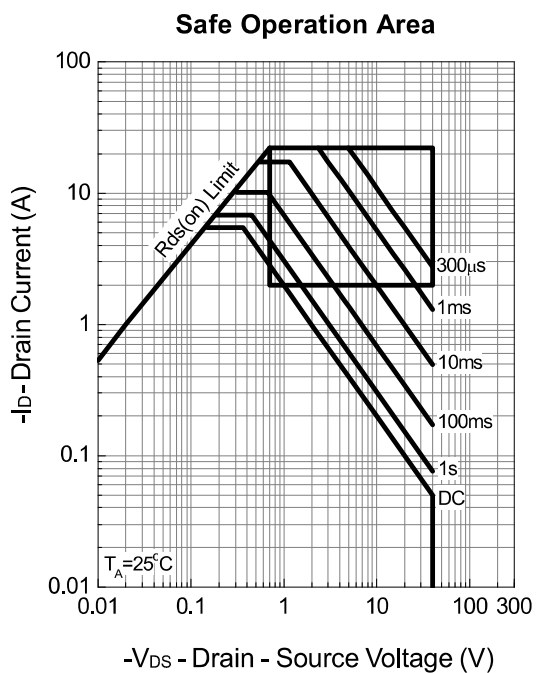
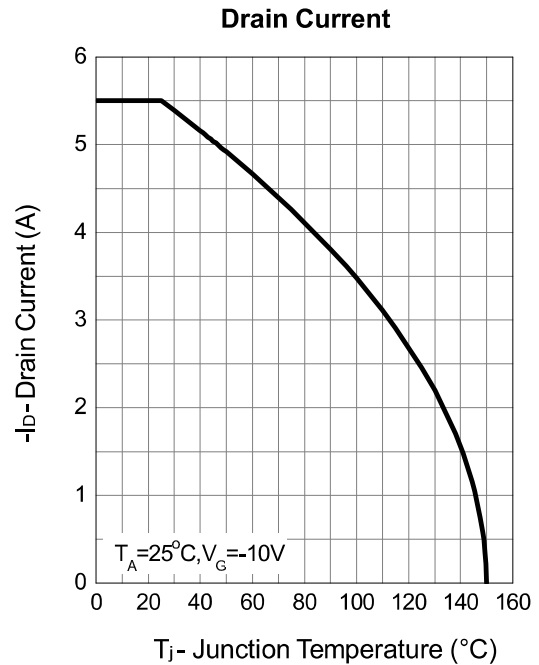
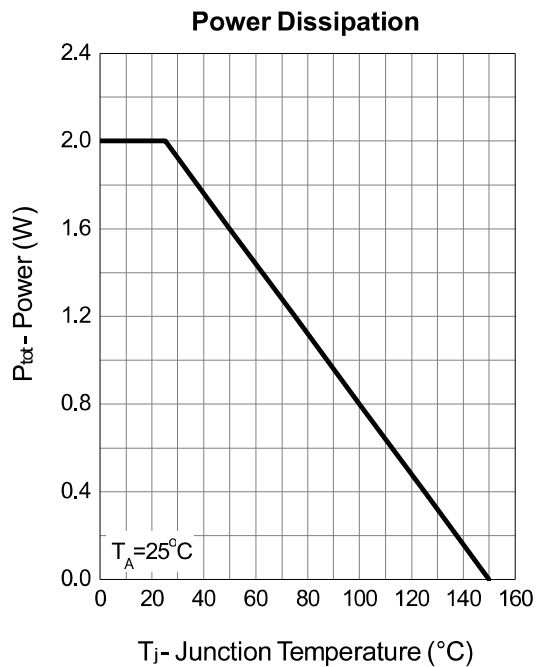
Capacitance



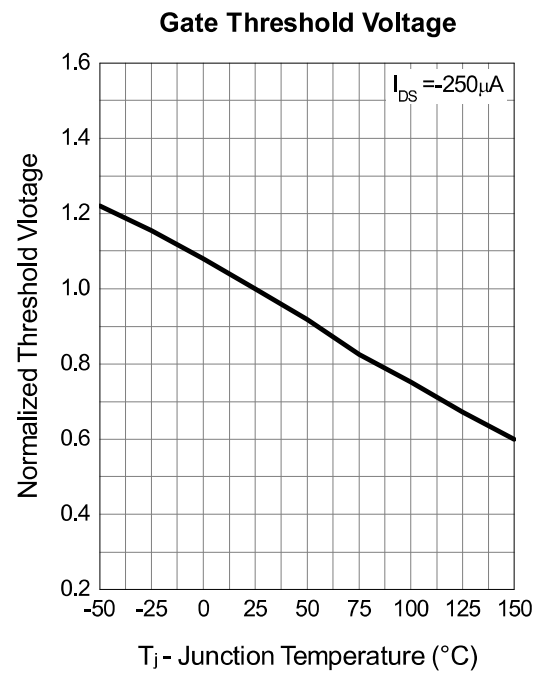
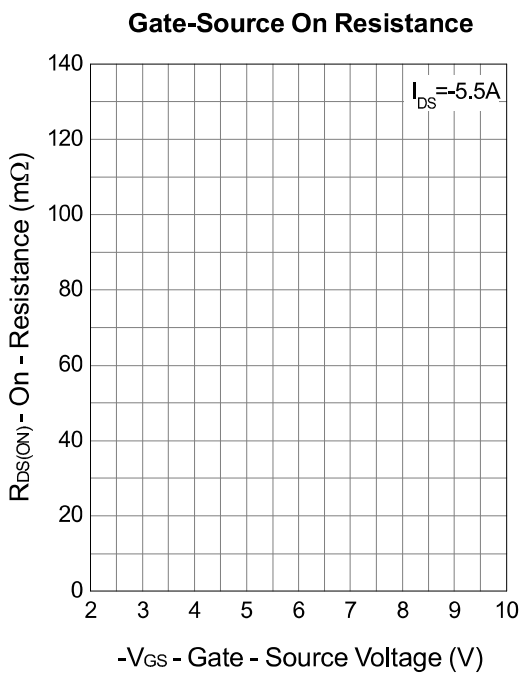
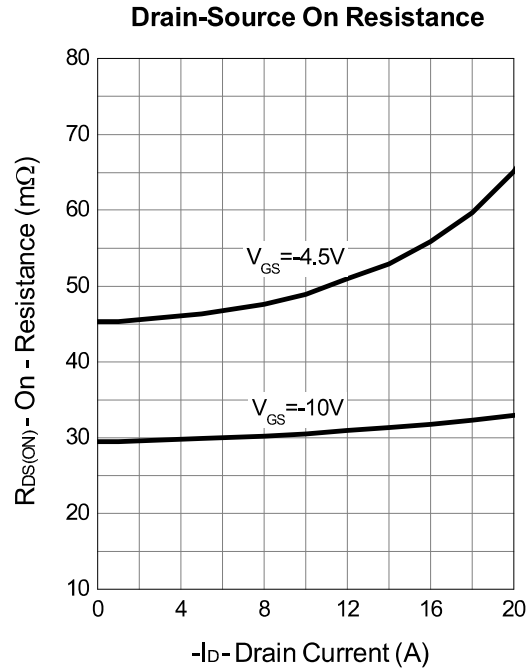
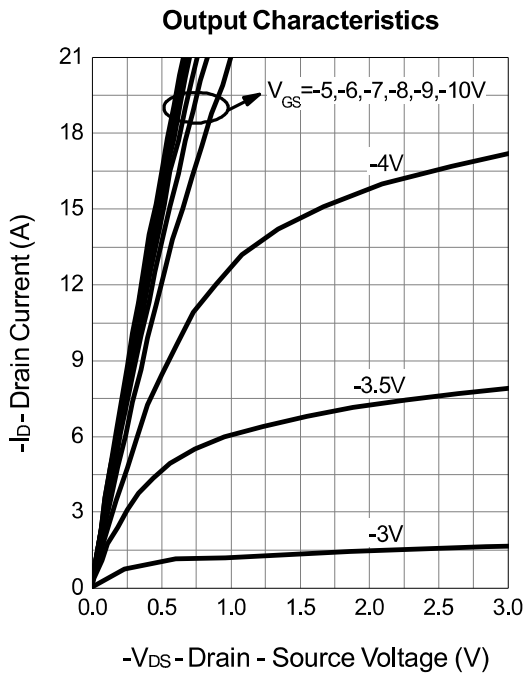
Gate Charge



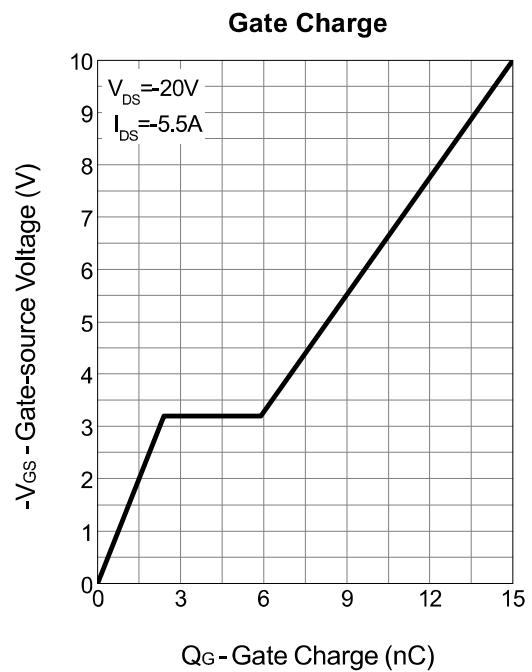
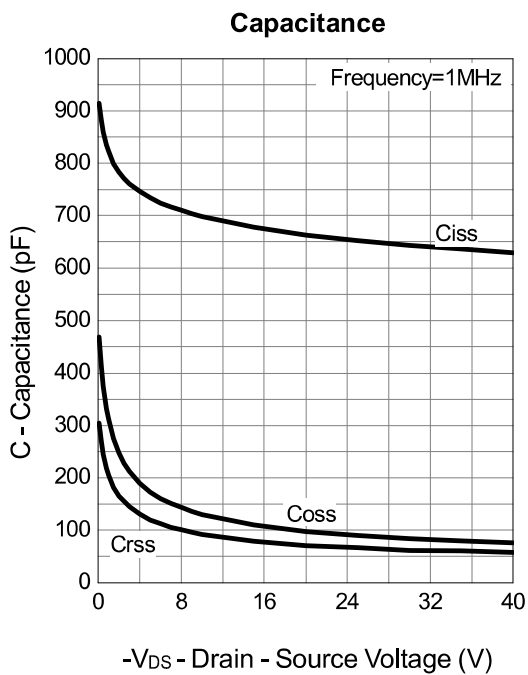
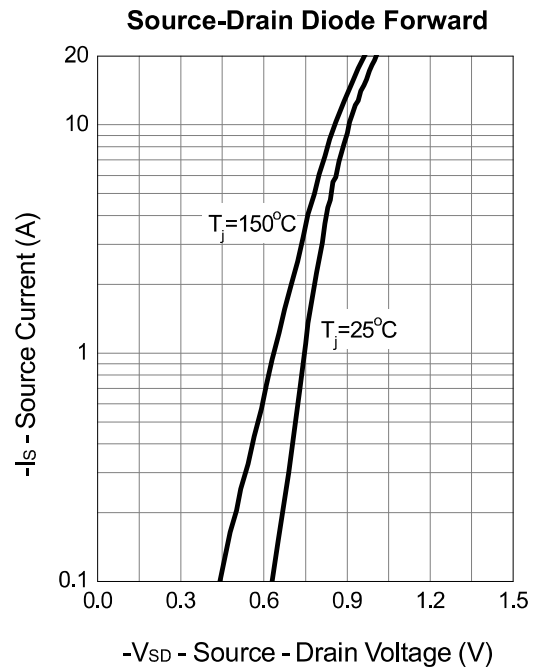
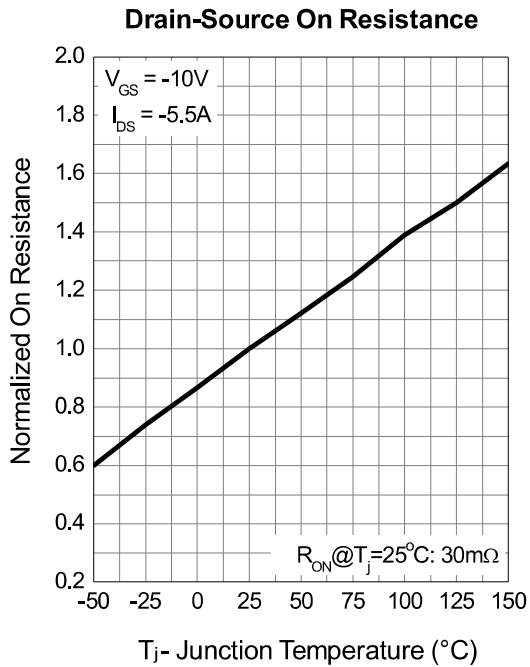
P Channel Typical Operating Characteristics



P Channel Typical Operating Characteristics (Cont.)

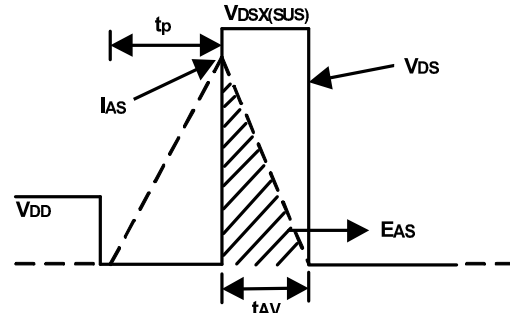
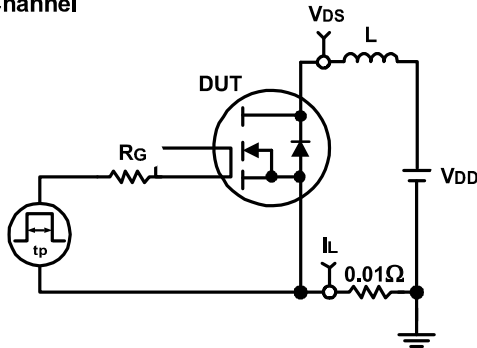


P Channel Typical Operating Characteristics (Cont.)

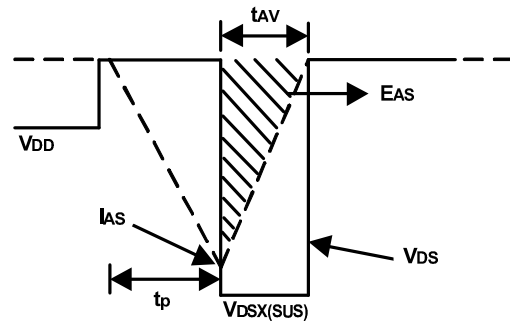
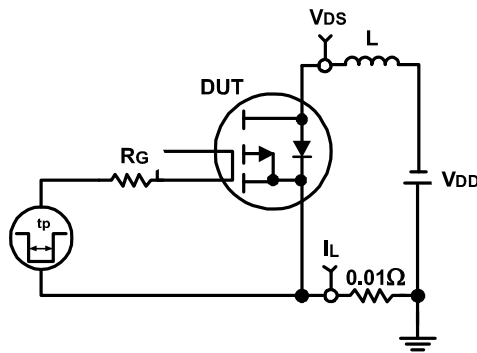


Avalanche Test Circuit and Waveforms

N Channel

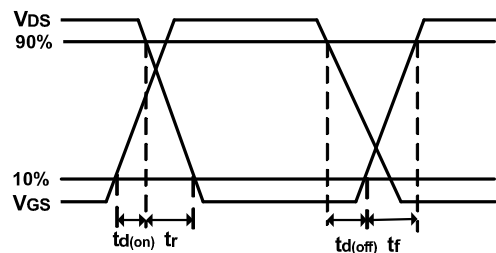
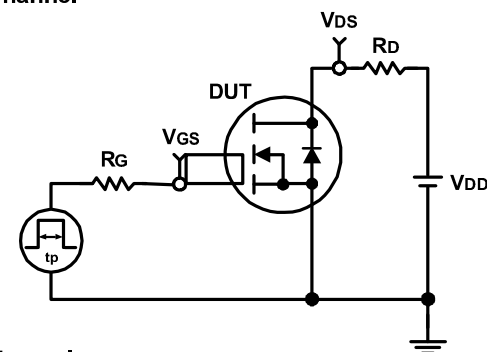


P Channel

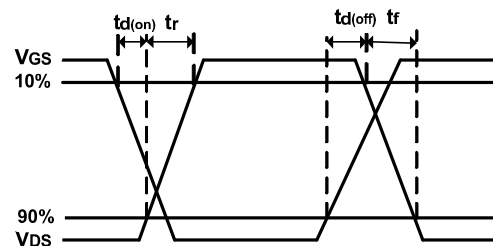
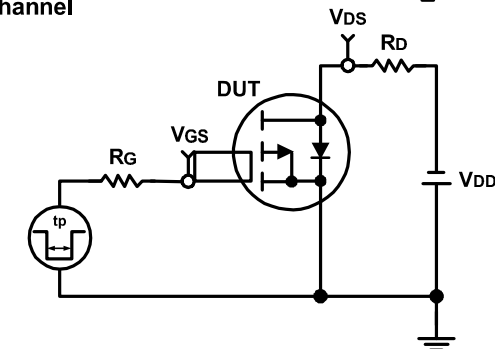


Switching Time Test Circuit and Waveforms

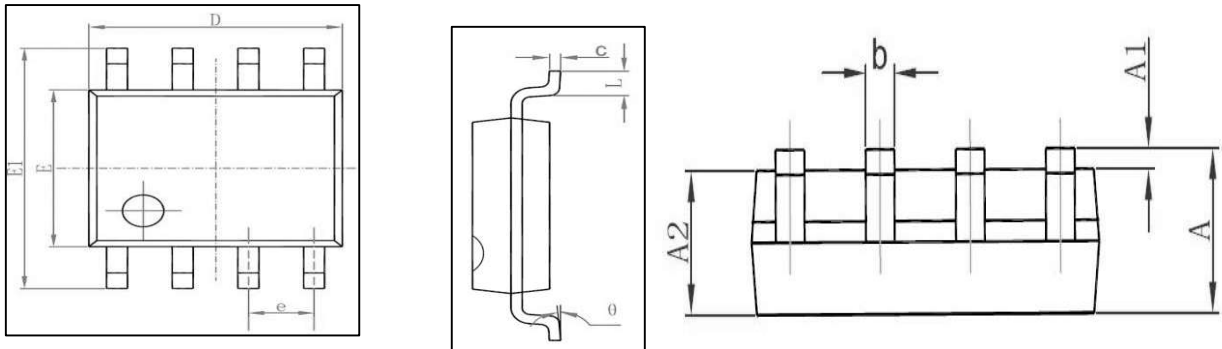
N Channel



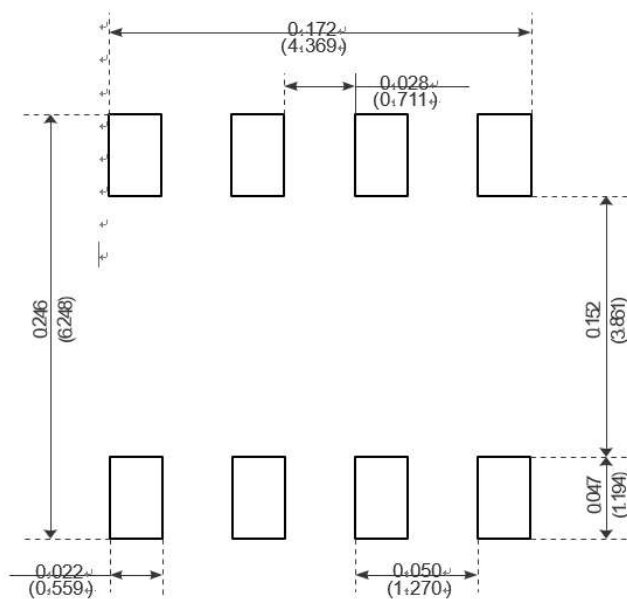
P Channel



SOP-8



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270 (BSC)		0.050 (BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°



Recommended Minimum Pads